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1-28-03
December 10, 2002

To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Ave.
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 09/846,536

05/02/01

W. T. Chu et al

"SELF ALIGNED, LOW CONTACT RESISTANCE,
VIA FABRICATION PROCESS"

GRP. Art. Unit 2811

O. Nadav

RESPONSE PATENT OFFICE ACTION

Dear Sir;

In response to the Office Action dated October 16, 2002, please amend the identified
application for patent as follows:

The commissioner is hereby authorized to charge payment of any additional fees involved
with added Claims and the like to Deposit Account No. 19-0033

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal
Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks,
Washington, D.C. 20231, on January 8, 2003.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date

[Signature]
1/8/03

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